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Appl. No. 09/888,002

**APPENDIX****VERSION WITH MARKINGS TO SHOW CHANGES MADE****In the Claims:**

25. A method for removing electrically conductive material from a face surface of a microelectronic substrate, comprising:

engaging the microelectronic substrate with a polishing surface of a polishing pad;

coupling the conductive material to a source of electrical potential;

removing at least a portion of the conductive material from the microelectronic substrate by passing a varying current through the conductive material while moving at least one of the microelectronic substrate and the polishing pad relative to the other and while the microelectronic substrate is engaged with the polishing pad; and

removing gas from a region between adjacent to the face surface of the microelectronic substrate ~~and/or~~ an electrode facing toward the face surface of at least ~~proximate to~~ the microelectronic substrate while the conductive material is removed from the microelectronic substrate.